

Applicati n No.: 09/849,457

Docket N .: JCLA6623

**AMENDMENTS****In The Claims:**

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**Claims 1-13 (canceled)**

**Claim 14. (currently amended)** A method for forming a light emitting device, the method comprising:

providing a covering layer;

providing a light emitting unit, comprising a metal cathode layer;

performing an evaporation depositing process, to form an active absorption layer on a surface of the covering layer; and

putting the covering layer with the surface having the active absorption layer, over at least a portion of the light emitting unit above the metal cathode layer.

**Claim 15. (original)** The method of claim 14, wherein the metal cathode layer comprises one selected from the group consisting of Li, Mg, and Ca.

**Claim 16. (original)** The method of claim 14, wherein the active absorption layer comprises one selected from the group consisting of Li, Mg, and Ca.

**Claims 17-20 (canceled)**

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**Claim 21. (new)** The method of claim 14, wherein the step of providing a light emitting unit further comprises:

providing a transparent substrate, wherein a transparent anode layer, a light emitting layer and the metal cathode layer are sequentially formed on the substrate; and

forming a sealant layer, at least covering the light emitting layer and the metal cathode layer;

wherein the covering layer is putted, by the covering surface, over at least a portion of the sealant layer above the metal cathode layer.

**Claim 22. (new)** The method of claim 14, wherein before the step of performing the evaporation deposition process, the method further comprises:

forming a recess region on the covering surface of the covering layer, wherein the active absorption layer is formed on a recessed surface of the recess region.

**Claim 23. (new)** The method of claim 14, wherein in the step of providing the covering layer, the covering layer comprises a cap-like layer to completely cover over the sealant layer, the transparent anode layer, light emitting layer, and the metal cathode layer.

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**Claim 24. (new)** The method of claim 23, wherein before the step of performing the evaporation depositing process, further comprises:

forming a recess region on the covering surface of the covering layer, whereby the active absorption layer is formed on a recessed surface of the recess region.

**Claim 25. (new)** The method of claim 23, wherein further comprises a clearance between the cap-like covering layer and the sealant layer.

**Claim 26. (new)** The method of claim 14, wherein the step of providing a light emitting unit further comprises:

providing a transparent substrate, wherein a transparent anode layer, a light emitting layer and the metal cathode layer are sequentially formed on the substrate; and

wherein in the step of performing an evaporation deposition process, the active absorption layer is formed at least covering the metal cathode layer;

forming a sealant layer, at least covering the light emitting layer and the metal cathode layer;

wherein the covering layer is putted, by the covering surface, over at least a portion of the sealant layer above the metal cathode layer.

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**Claim 27. (new)** The method of claim 14, wherein the step of providing a light emitting unit further comprises:

providing a transparent substrate, wherein a transparent anode layer, a light emitting layer and the metal cathode layer are sequentially formed on the substrate;

optionally forming a sealant layer, at least covering the metal cathode layer;

etching the covering layer to form a recess region on the covering layer at a covering surface with respect to the metal cathode layer, and forming a trench enclosing the recess region;

wherein in the step of performing an evaporation deposition process, the active absorption layer is formed on the covering layer within the recess region;

coating a gluing layer on a portion of the covering layer between the trench and the recess region; and

adhering the covering layer onto the transparent substrate.

**Claim 28. (new)** The method of claim 27, wherein the step of etching covering layer comprises performing a sand-jet etching process.

**Claim 29. (new)** The method of claim 28, wherein the step of etching covering layer comprises performing a sand-jet etching process with etchant of aluminum oxide particles.

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**Claim 30. (new)** The method of claim 14, wherein the step of providing a light emitting unit further comprises:

providing a transparent substrate, wherein a transparent anode layer, a light emitting layer and the metal cathode layer are sequentially formed on the substrate;

optionally forming a sealant layer, at least covering the light emitting layer and the metal cathode layer;

wherein in the step of performing an evaporation deposition process, the active absorption layer is formed on the covering layer within the recess region;

forming two frit lines on the covering layer, enclosing the active absorption layer, wherein a clearance between the two frit lines is reserved;

properly dripping a sealant material on the clearance; and

adhering the covering layer on the transparent substrate layer through the sealant material, wherein the active absorption layer is above the metal cathode layer.

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